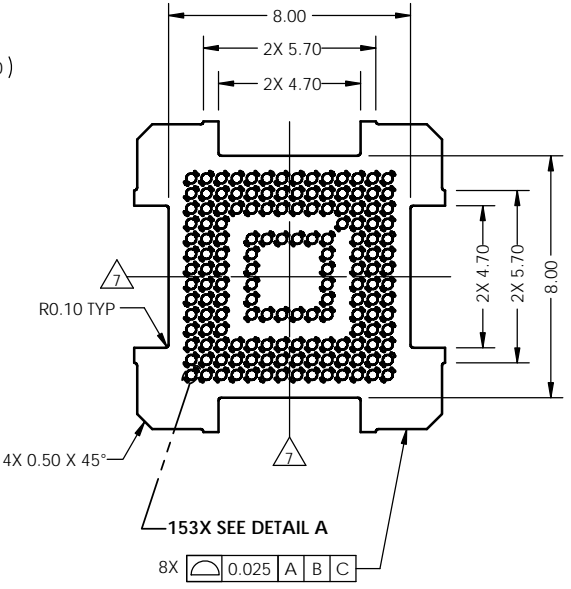
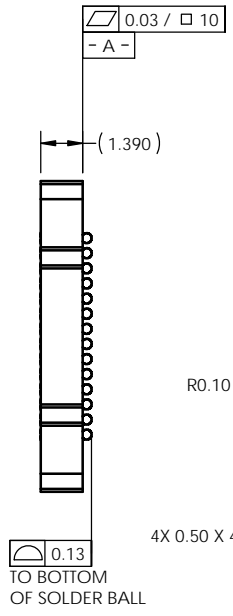
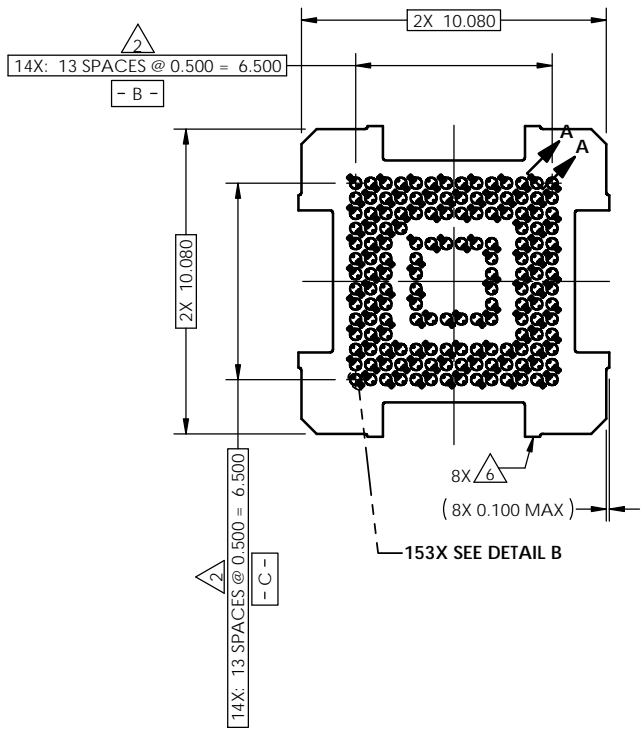
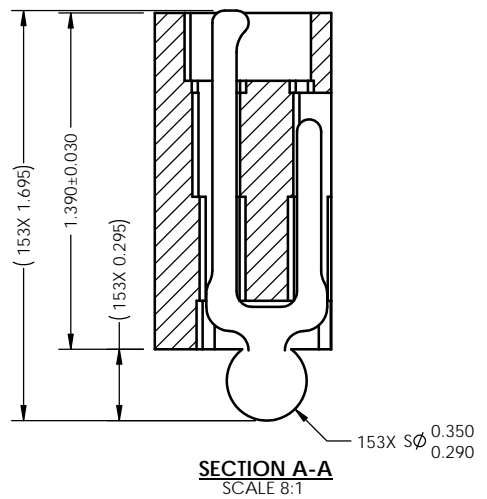
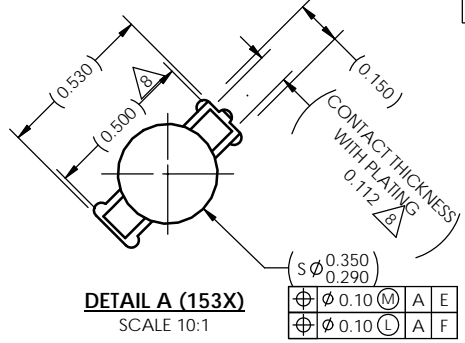
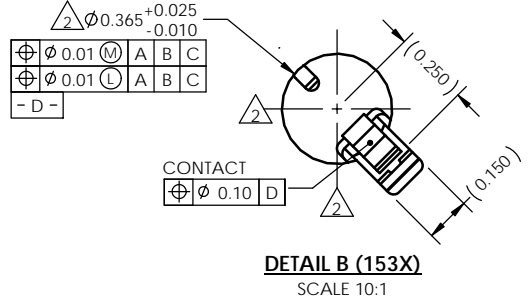


REV	ECO	BY	DESCRIPTION	APV	DATE
A	31419	AS	Initial Design	MP	11/11/13



- Notes:
- Reference HSIO Technologies specification 700001-0001 for solder attachment.
 - Locates center of contact/ slot.
 - Reference HSIO Technologies specification 700001-0002 for application notes.
 - Footprint part number is 104311-0405.
 - Datums **- B -** and **- C -** are determined by $\phi 0.365$ features on corner slots.
 - Tooling marks permitted. Maximum 0.10 protrusion (shown).
 - E -** Center of ball pattern.
 - F -** Center of contact.

Parts List	
Part Number	Description
103864-0033	PRESS, DEVICE INSERT, G40 10.0 X 10.0 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
104553-0318	STEN FLEX, 153G4010-0.50 (SOLD SEPARATELY)



UNLESS OTHERWISE SPECIFIED:

DIMENSIONS ARE IN MILLIMETERS

TOLERANCES -

ANGULAR ± 1°

XX ±0.25

XXX ±0.10

XXXX ±0.050

NAME	AS	DATE	11/11/13
DRAWN	AS	DATE	11/11/13
CHECKED	MP	DATE	11/11/13

LEGEND:	
△	NOTE CALLOUT
○	REVISION CHANGE
○	ITEM NUMBER

HSIO technologies

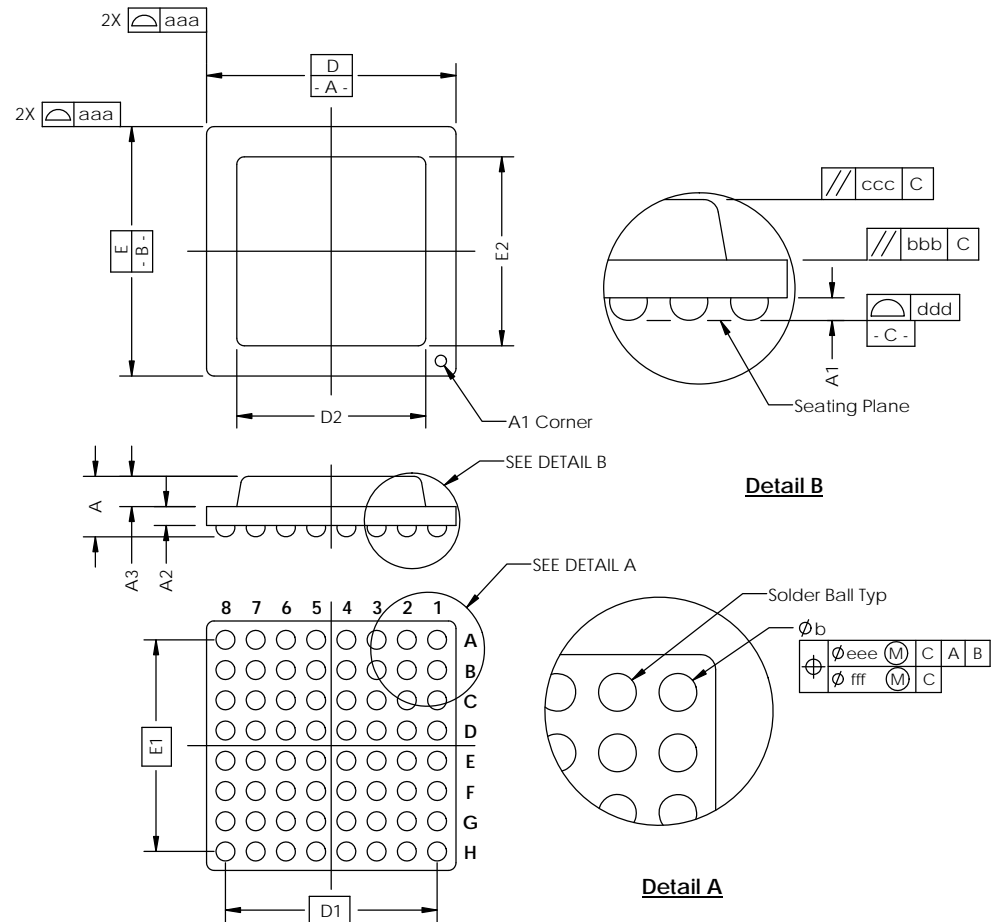
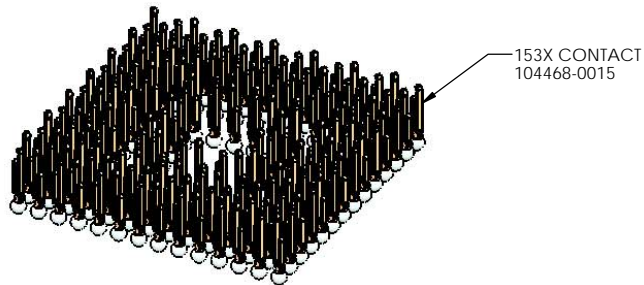
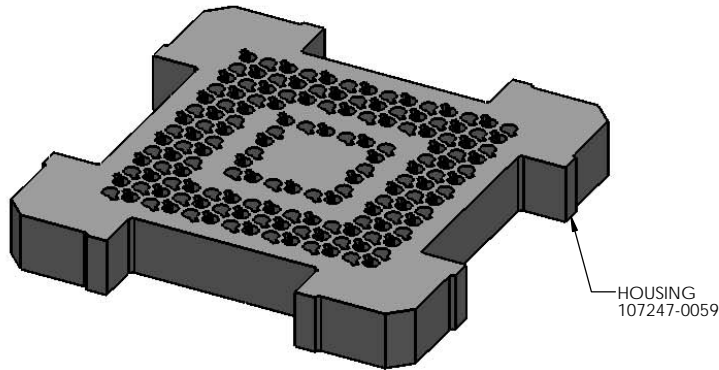
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HSIO TECHNOLOGIES, LLC.	
13300 67th AVENUE NORTH	
MAPLE GROVE, MINNESOTA 55311	
763-447-6260	
TITLE: SCKT, 153G4010-0.50, W/ EUTECTIC SOLDER BALLS	
DWG. NO.	REV
108387-0059	A
SCALE: 10:1	SIZE: C
SHEET 1 OF 2	

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	153	Package Size	D	10.00
Columns	ND	14		E	10.00
Rows	NE	14	Ball Spacing	D1	6.500
Pitch	e	0.50		E1	6.500
Ball Size	b	0.30±0.05	Encapsulant/ Top Size	D2	n/a
Total Thickness	A	n/a		E2	n/a
Ball Height	A1	0.225 min.	Pattern Style	IRREGULAR*	
Substrate Thickness	A2	n/a	Perimeter Rows	3	
Top Thickness	A3		Center Array	n/a	
Form Tolerances					
Edge	aaa	0.10	Bottom	ddd	0.08
Substrate	bbb	0.10	Position	eee	0.15
top	ccc	0.10	Position	fff	0.05

All dimensions are in millimeters.
* See footprint for pattern details.



Generic Representation with Full Grid Array

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	HSIQ TECHNOLOGIES, LLC. 13300 67th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260
DIMENSIONS ARE IN MILLIMETERS	DRAWN	AS 11/11/13	
TOLERANCES: ANGULAR: ± 1° XX ±0.05 XXX ±0.10 XXXX ±0.050	CHECKED	MP 11/11/13	
LEGEND:			TITLE:
△ NOTE CALLOUT ○ REVISION CHANGE ○ ITEM NUMBER			SCKT, 153G4010-0.50, W/ EUTECTIC SOLDER BALLS
		DWG. NO.	REV
		108387-0059	A
		SCALE: 5:1	SIZE: C SHEET 2 OF 2